HT16523
5x7 Dot Character VFD Controller & Driver

Feature

- Logic voltage: 2.7V~5.5V
- High voltage: 40V (max.)
- 3-line serial interface
- Alphanumeric and symbolic display using integrated ROM
- 16 x 8-bit display data RAM (DDRAM)
- Integrated 5x7 dot ROM containing 248 character set
- 8 user-defined characters stored in character generator RAM (CGRAM)
- Additional symbol display data stored in 16 x 8-bit RAM (ADRAM)
- Display content:
  16 columns by 1 row + 32 symbols - each column has 1 digit character with 2 symbols
- Supports display output: 35-segment & 16-grid
- Supports symbol output: 2-symbol & 16-grid
- Supports 2-pin general output port - static operation
- Fully integrated oscillator circuit
- 64-pin LQFP package

Applications

- Consumer products panel function control
- Industrial measuring instrument panel function control
- Other similar application panel function control
- Suitable for POS terminals or message displays

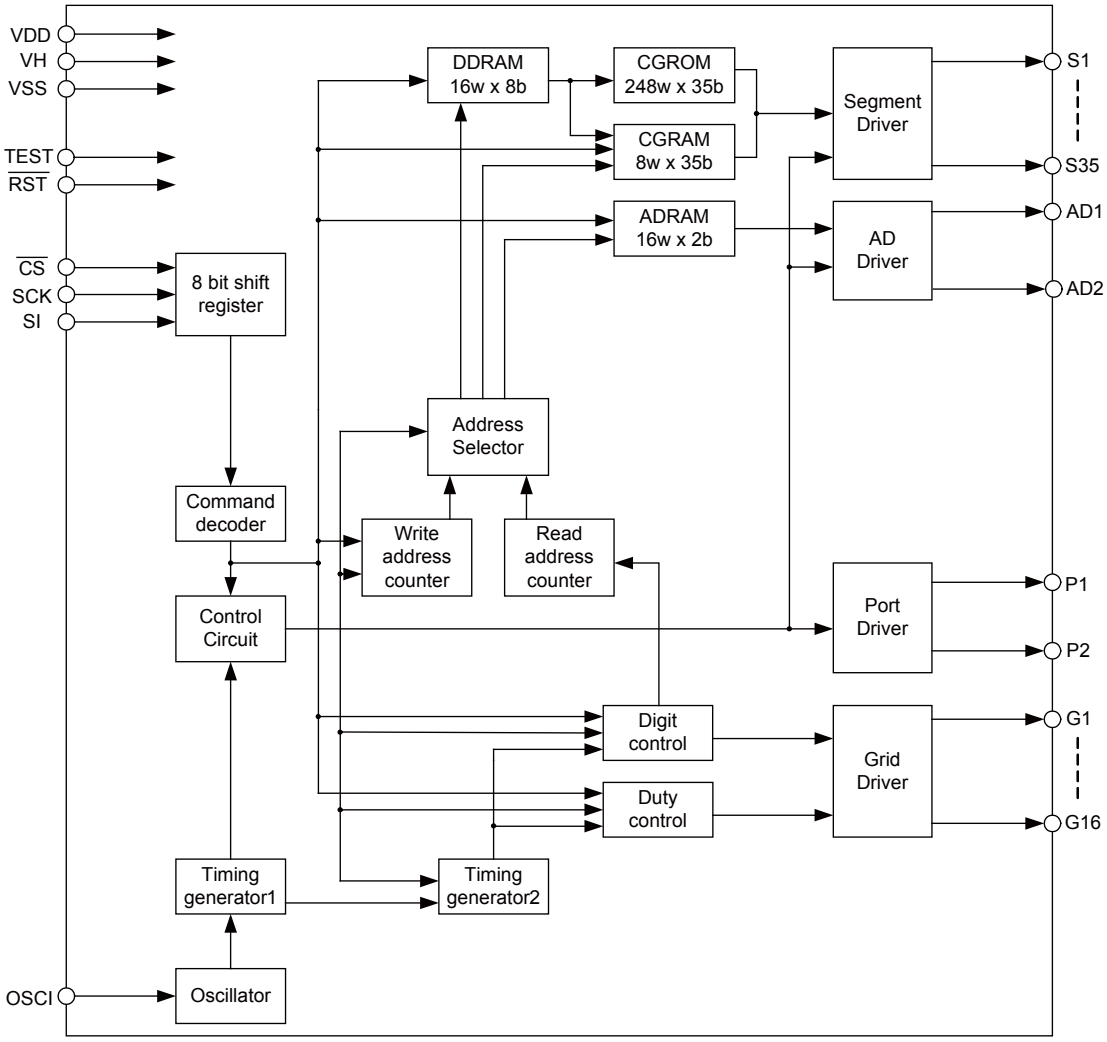
General Description

The HT16523 device is a dot matrix Vacuum Fluorescent Display, VFD, controller/driver which displays characters, numerics and symbols. Dot matrix VFD driving signals are received via a 3-line serial interface driven by an externally connected microcontroller. The display data is stored in the internal ROM and RAM for character and symbol display.

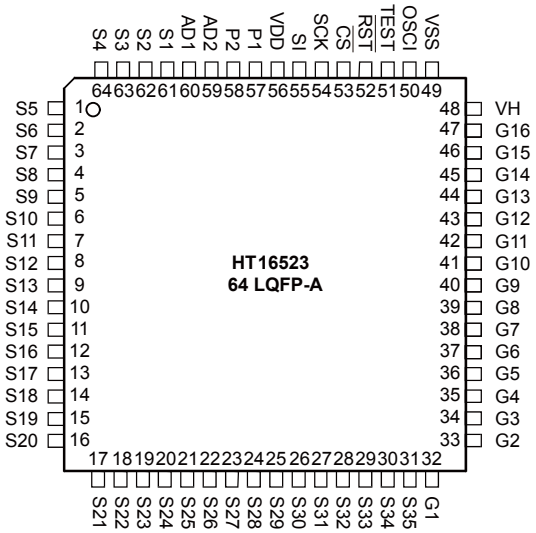
Ordering Information

Part Number	Information
HT16523-002	64-pin LQFP package with ROM code 002
HT16523-003	64-pin LQFP package with ROM code 003

Block Diagram



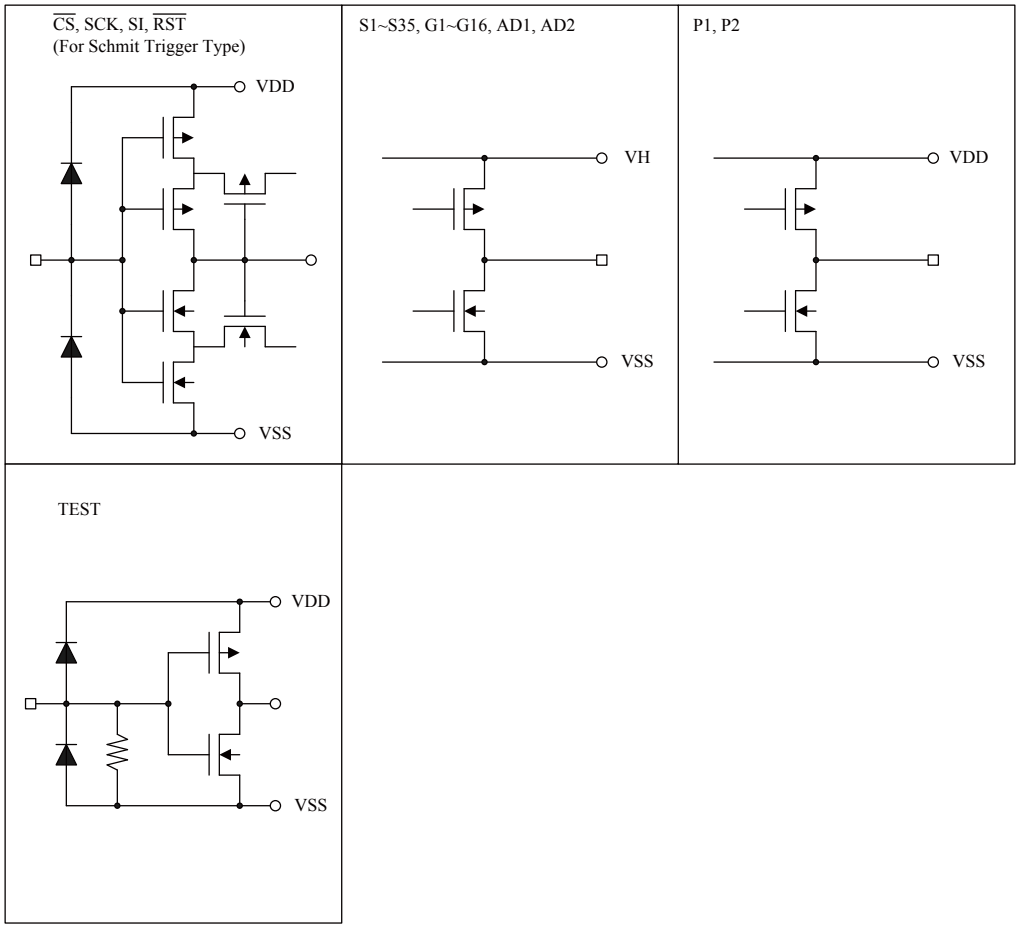
Pin Assignment



Pin Description

Pin Name	I/O	Description
Power Supply Pins		
VDD	—	Positive power supply for logic circuits.
VH	—	Power supply for VFD driver circuits.
VSS	—	VSS - ground pin.
Microcontroller Interface Pins		
$\overline{CS}$	I	Chip select pin When “Low”, the device is active.
SCK	I	Serial clock input Shift clock input with data written on the SCK rising edge.
SI	I	Serial data input. The serial data is first shifted from LSB.
$\overline{RST}$	I	Initialize all the internal registers and commands. All segments and digits are fixed at “Low” level.
TEST	I	When “Low” or open, the device is in normal mode. When “High”, the device is in test mode.
Output Pins		
S1~S35	O	High-voltage segment output pins.
G1~G16	O	High-voltage grid output pins.
AD1,AD2	O	High-voltage additional data segment output pins.
P1,P2	O	General port output. Static operation output - can drive LEDs
Oscillator pin		
OSCI	I	Oscillator input pin Connected to an external resistor and capacitor to generate the oscillation frequency.

Approximate Internal Connections



Absolute Maximum Ratings

Logic Supply Voltage..... Vss-0.3V to Vss+6.0V
Driver Supply Voltage..... Vss-0.3V to Vss+45V
Input Voltage.. ..... Vss-0.3V to V_{DD}+0.3V
Output Voltage ..... Vss-0.3V to V_{DD}+0.3V
Grid output current..... -20mA to 4mA
Segment output current..... -10mA to 4mA
AD output current ..... -15mA to 4mA
General port output current..... -20mA to 40mA
Storage Temperature ..... -55°C to 125°C
Operation Temperature ..... -40°C to 85°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

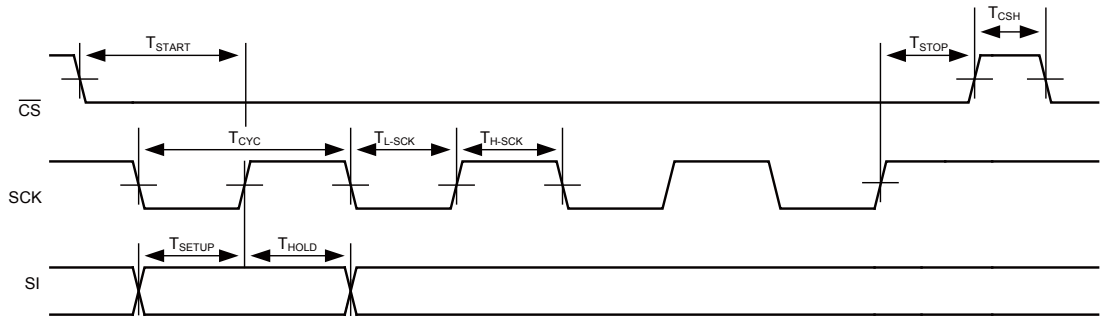
D.C. Characteristics

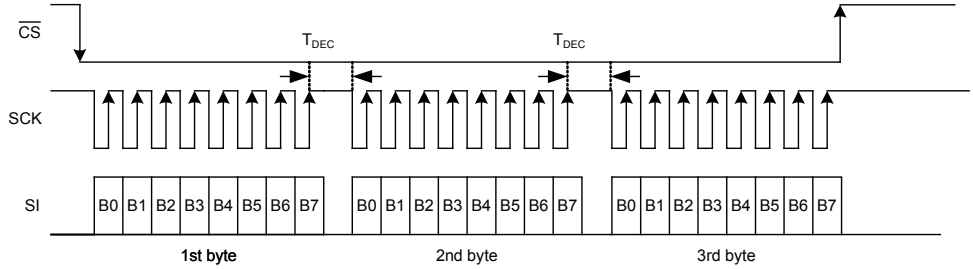
V_H=40V, V_{SS}=0V, Ta=-40°C ~ 85°C

Symbol	Parameter	Test Condition		Min.	Typ.	Max.	Unit
		V_{DD}	Condition				
V_{DD}	Logic Supply Voltage	—	—	2.7	5.0	5.5	V
V_H	VFD Supply Voltage	—	—	10	—	40	V
I_{DD1}	VDD Operating Current	5V	f_{OSC}=2MHz, no load, Duty=15/16, Digit=1 to 16. All output lights On, MCU no write data or command, P2 and P1=high	—	—	2	mA
		3V		—	—	1	
I_{DD2}	VDD Operating Current	5V	f_{OSC}=2MHz, no load, Duty=15/16, Digit=1 to 16. Stop scan MCU no write data or command, P2 and P1=high	—	—	2	mA
		3V		—	—	1	
I_{STB}	VDD Standby Current	5V	Standby mode	—	2	10	μA
		3V		—	1	5	μA
I_{H1}	VH Operating Current	—	f_{OSC}=2MHz, no load, Duty=15/16, Digit=1 to 16, All output lights On, MCU no write data or command, P2 and P1=high	—	—	1	mA
I_{H2}	VH Operating Current	—	f_{OSC}=2MHz, no load, Duty=15/16, Digit=1 to 16, Stop scan MCU no write data or command, P2 and P1=high	—	—	20	μA
I_{H_STB}	VH Standby Current	—	Standby mode	—	—	20	μA
V_{IH}	High Level Input Voltage	5V	$\overline{CS}$, SCK, SI, $\overline{RST}$	0.8V_{DD}	—	V_{DD}	V
		3V					
V_{IL}	Low Level Input Voltage	5V	$\overline{CS}$, SCK, SI, $\overline{RST}$	0	—	0.2V_{DD}	V
		3V					
I_{IH}	High Level Input Current	5V	V_{IH}=V_{DD}, $\overline{CS}$, SCK, SI, $\overline{RST}$	—	—	1	μA
		3V					
I_{IL}	Low Level Input Current	5V	V_{IL}=0V, $\overline{CS}$, SCK, SI, $\overline{RST}$	-1	—	—	μA
		3V					
V_{OH1}	High Level Output Voltage	5V	G1~G16, I_{OH1}=-15mA	37	—	—	V
		3V					
V_{OH2}		5V	AD1, AD2, I_{OH2}=-7mA	38	—	—	V
		3V					
V_{OH3}		5V	S1~S35, I_{OH3}=-1mA	38	—	—	V
		3V					
V_{OH4}		5V	P1, P2 I_{OH4}=-2mA	0.9V_{DD}	—	—	V
		3V	P1, P2 I_{OH4}=-1mA	0.9V_{DD}	—	—	
V_{OL1}	Low Level Output Voltage	5V	G1~G16, I_{OL1}=1mA	—	—	2	V
		3V					
V_{OL2}		5V	AD1, AD2, I_{OL2}=1mA	—	—	2	V
		3V					
V_{OL3}		5V	S1~S35, I_{OL3}=1mA	—	—	2	V
		3V					
V_{OL4}		5V	P1, P2 I_{OL4}=20mA	—	—	1	V
		3V	P1, P2 I_{OL4}=10mA	—	—	1	
R_{PD}	Pull Down Resistor	5V	TEST PIN	—	50	100	KΩ
		3V		—	100	200	KΩ

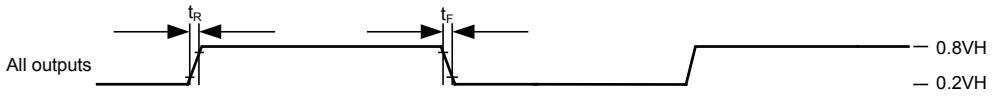
A.C. Characteristics

Serial Interface Timing





Output Timing

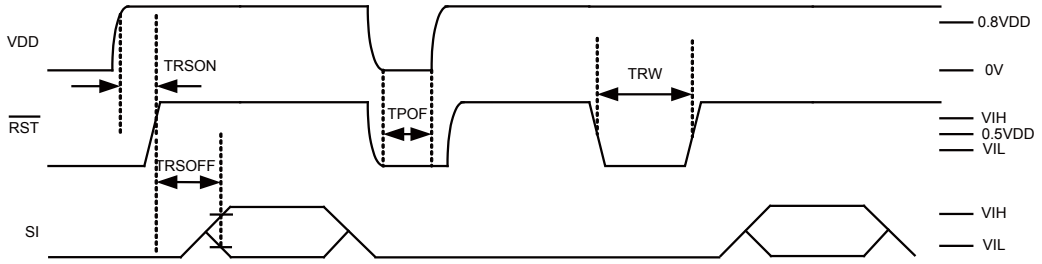


V_H=40V, V_{SS}=0V, Ta =-40°C ~ 85°C

Symbol	Parameter	Test Condition		Min.	Typ.	Max.	Unit
		V_{DD}	Condition				
f_{OSC}	Oscillation Frequency	5V	R1=120kΩ, C1=0.1μF	1.5	2	2.5	MHz
		3V					
f_{FR}	Frame Frequency	5V	Digit=1 to 16, R1=120kΩ, C1=0.1μF	183	244	305	Hz
		3V					
T_{CYC}	Write Cycle Time	5V	SCK	—	—	2	MHz
		3V		—	—	2	
$T_{L\text{-}SCK}$	Low Pulse of SCK	5V	SCK	250	—	—	ns
		3V		250	—	—	
$T_{H\text{-}SCK}$	High Pulse of SCK	5V	SCK	250	—	—	ns
		3V		250	—	—	
T_{SETUP}	Data Setup Time	5V	SCK, SI	250	—	—	ns
		3V		250	—	—	
T_{HOLD}	Data Hold Time	5V	SCK, SI	250	—	—	ns
		3V		250	—	—	
T_{START}	Command Start Wait Time	5V	SCK, SI	250	—	—	ns
		3V		250	—	—	
T_{STOP}	Command Stop Wait Time	5V	SCK, $\overline{CS}$	16	—	—	μs
		3V		16	—	—	
T_{CSH}	$\overline{CS}$ Off Time	5V	—	250	—	—	ns
		3V		250	—	—	
T_{DEC}	Command/Data Decode Time	5V	—	8	—	—	μs
		3V		8	—	—	
t_R	All Output Slew Rate	5V	Ci=100 pF, t_R=20 to 80%	—	—	2	μs
		3V					
t_F		5V	Ci=100 pF, t_F=80 to 20%	—	—	2	μs
		3V					

Reset and Wake-up Timing

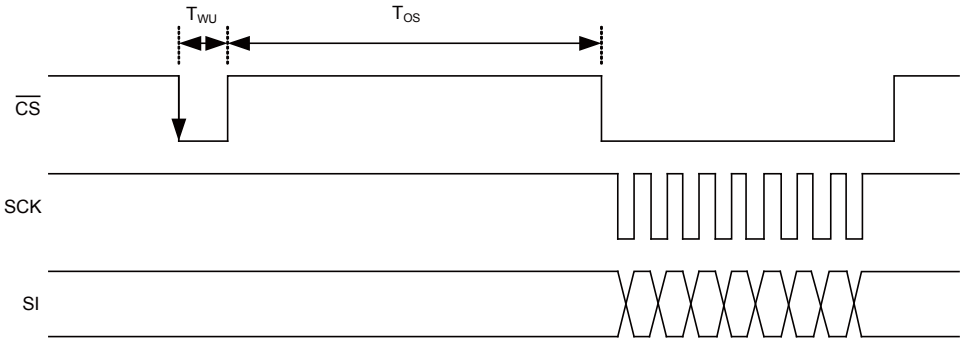
Hardware Reset



Ta=-40°C ~ 85°C

Symbol	Parameter	Test Condition		Min.	Typ.	Max.	Unit
		V_{DD}	Condition				
T_{RSON}	Oscillator Stable Time	5V	$\overline{RST}$ signal is an external input from a microcontroller etc.	250	—	—	ns
		3V		250	—	—	
		5V	R2=1kΩ, C2=0.1μF	—	1000	—	μs
		3V		—	1000	—	
T_{POF}	VDD Off Time	5V	VDD drop down to 0V	40	—	—	μs
		3V		10	—	—	ms
T_{RW}	$\overline{RST}$ Pulse Width	5V	$\overline{RST}$ signal is an external input from a microcontroller etc.	400	—	—	ns
		3V		400	—	—	
T_{RSOFF}	SI Wait Time	5V	—	3	—	—	μs
		3V		3	—	—	

Wake-up Timing

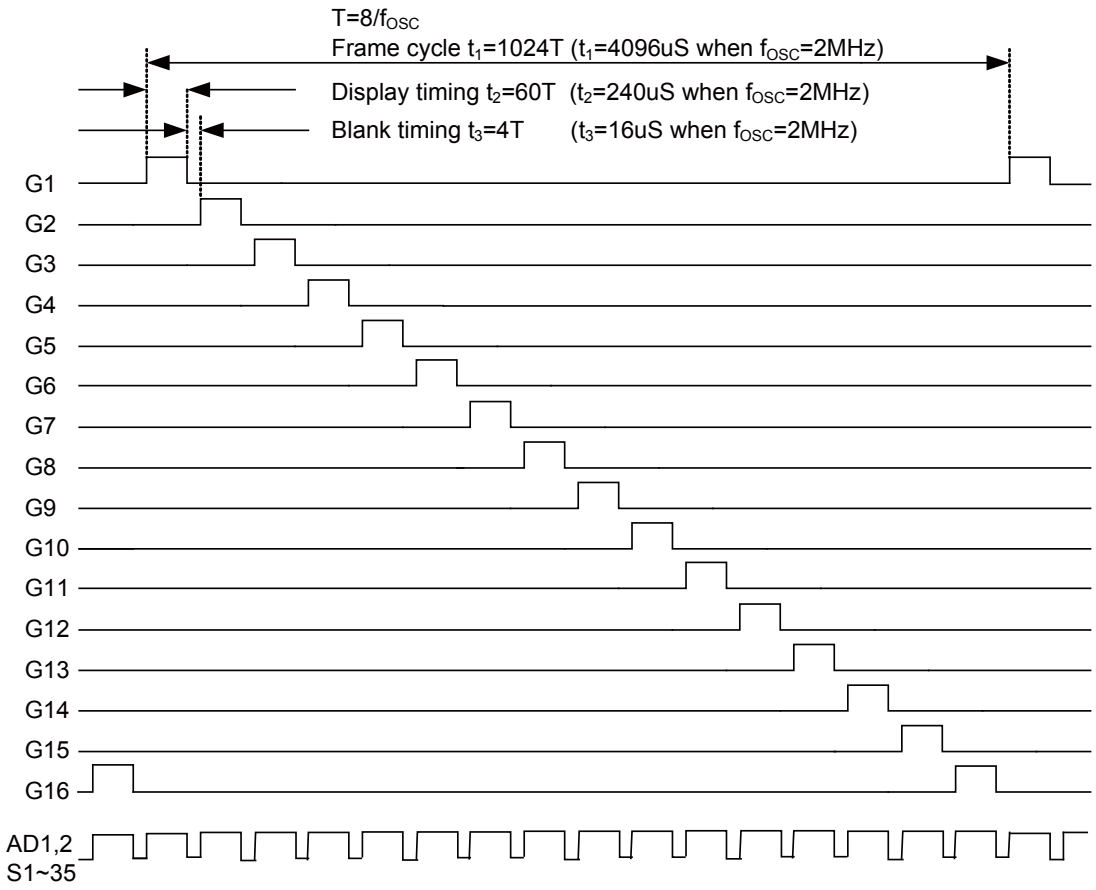


Ta=-40°C ~ 85°C

Symbol	Parameter	Test Condition		Min.	Typ.	Max.	Unit
		V_{DD}	Condition				
T_{WU}	Wake-up Time	5V	—	200	—	—	ns
		3V					
T_{OS}	Oscillation Stable Time	5V	—	1000	—	—	μs
		3V					

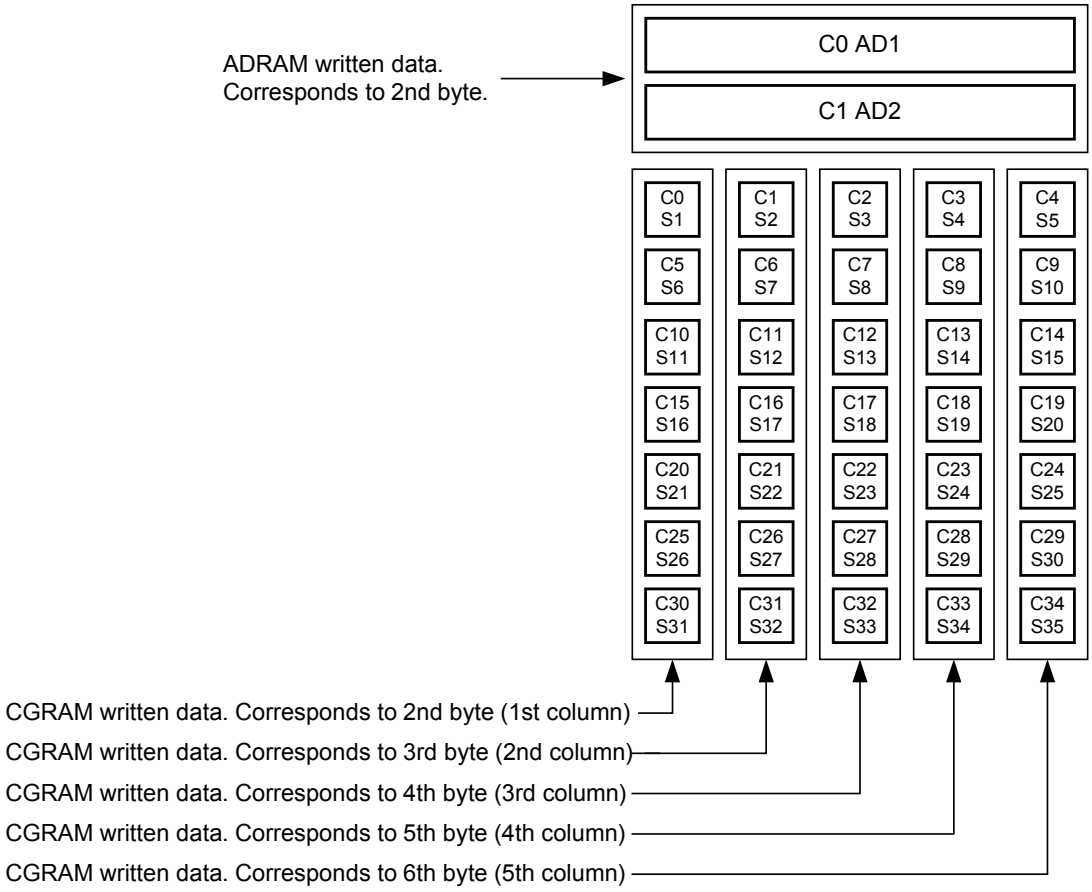
Digit Output Timing

For 16-digits display, at a duty of 15/16



Segment and AD Position

Positional relationship between S1~S35 and AD1 ~ AD2 - single digit



Command Table

Function	Byte	R/W	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)	Note	Default
DDRAM data write	1st	W	0	0	0	*	X3	X2	X1	X0	Xn: Address specification for each RAM	00H
DDRAM data	2nd	W	C7	C6	C5	C4	C3	C2	C1	C0	Cn: character code specification for each RAM	—
CGRAM data write	1st	W	0	0	1	*	*	X2	X1	X0	Xn: Address specification for each RAM	20H
CGRAM Data	2nd	W	*	C30	C25	C20	C15	C10	C5	C0	Cn: character code specification for each RAM	—
CGRAM Data	3rd	W	*	C31	C26	C21	C16	C11	C6	C1		—
CGRAM Data	4th	W	*	C32	C27	C22	C17	C12	C7	C2		—
CGRAM Data	5th	W	*	C33	C28	C23	C18	C13	C8	C3		—
CGRAM Data	6th	W	*	C34	C29	C24	C19	C14	C9	C4		—
ADRAM data write	1st	W	0	1	0	*	X3	X2	X1	X0	Xn: Address specification for each RAM	40H
ADRAM Data	2nd	W	*	*	*	*	*	*	C1	C0	Cn: character code specification for each RAM	—
General output port set	1st	W	0	1	1	*	*	*	P2	P1	Pn: General output port status specification	63H
Display duty set	1st	W	1	0	0	*	*	D2	D1	D0	Dn: display duty specification	80H
Number of digits set	1st	W	1	0	1	*	*	K2	K1	K0	Kn: Number of digits specification	A0H
All lights ON/OFF	1st	W	1	1	0	*	D	S	H	L	D: display on/off instruction S: standby mode instruction H: all lights ON instruction L: all lights OFF instruction	C0H
TEST mode	1st	W	1	1	1	0	0	0	0	0	For HOLTEK internal testing	E0H

Command and Data Transfer Methods

Complete access to the VFD driver consists of display commands and the display data. The number of transmitted data bytes for a complete access depends upon the command and memory type as the Command Table shows. The display control commands and data are transmitted using a 3-wire serial interface from the host MCU. The following steps show how the operation of the serial interface circuitry.

- Setting the $\overline{CS}$ pin to a "Low" level will enable a data transfer.
- Data is 8-bits wide and is sequentially shifted-in on the SI pin from LSB to MSB (LSB first)
- Data shifted into the register is ready at the rising edge of the serial shift clock, SCK. If the 8-bit data is to be written in, then internal signals are automatically generated and the data will be written into the corresponding register and RAM.
- Setting the $\overline{CS}$ pin to "High" will disable the command and data transfer
- When data is written into the RAM area including DDRAM, ADRAM and CGRAM continuously, the command used to specify the RAM area is contained in the first shifted-in command byte together with the start address. Then the RAM address will be internally incremented by 1 automatically. Therefore, it is not necessary to specify the start address of the data to be written after the command byte.

Reset Function

When the $\overline{RST}$ pin is set to "Low", the module is initialized to the following conditions:

- Address will be reset to 00H for each RAM including DDRAM, ADRAM and CGRAM
- The contents of the RAM including DDRAM, ADRAM and CGRAM are undefined.
- All general output ports go "High".
- Display duty setting will be reset to 8/16 duty (register value D2, D1, D0=0, 0, 0).
- Number of digits setting will be reset to 16 digits (register value K2, K1, K0=0, 0, 0).
- All display lights ON/OFF settings will be switched to the "display off" mode (register value D,S,H,L=0,0,0,0)
- All segment outputs go "Low".
- All AD outputs go "Low".
- All grid outputs go "Low".

Note: After a power on reset, all the RAM, including DDRAM, ADRAM and CGRAM, will be cleared.

Functional Description

Timing Generation Circuit

A timing generation circuit generates timing signals for the operation of internal circuits such as the DDRAM, CGRAM, CGROM and ADRAM.

VFD Driver Circuit

The VFD driver circuit consists of 16 grid signal drivers and 35 segment signal drivers. When the number of digits are selected by a corresponding command, the required grid signal drivers automatically output drive waveforms, while the other grid signal drivers continue to output non-selection waveforms. Sending serial data is latched when the display data character pattern corresponds to the last address of the display data RAM (DDRAM).

Data Display RAM - DDRAM

The Display Data RAM (DDRAM) stores the display data in 8-bit character codes. Its extended capacity is 16x8 bits or 16 characters.

DDRAM data write command

Byte	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1st	W	0	0	0	*	X3	X2	X1	X0
2nd	W	C7	C6	C5	C4	C3	C2	C1	C0
3rd	W	C7	C6	C5	C4	C3	C2	C1	C0
4th	W	C7	C6	C5	C4	C3	C2	C1	C0
:	:	:	:	:	:	:	:	:	:

*: Don't care

The DDRAM data write command descriptions are shown in the following:

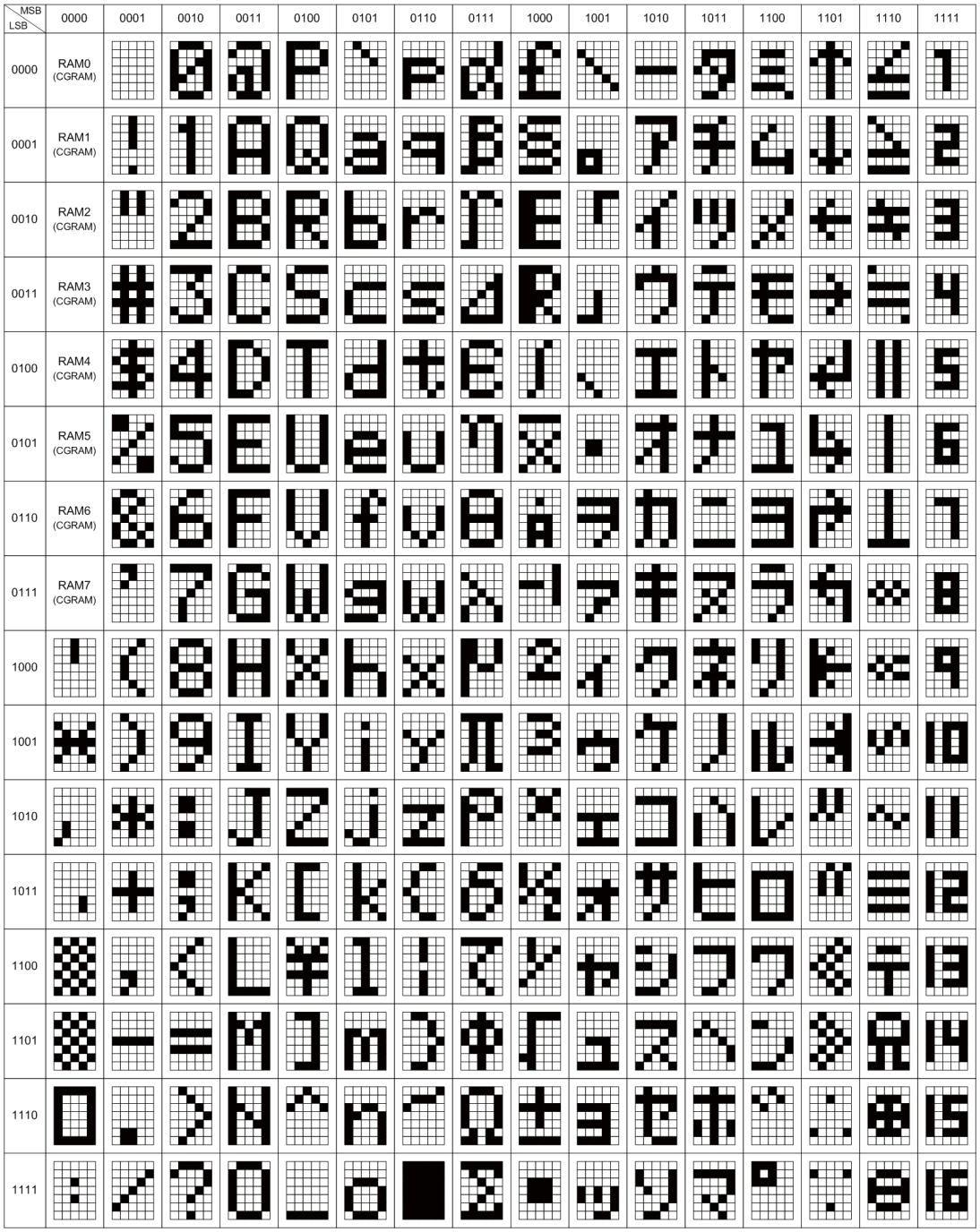
- X3~X0: DDRAM address is for 16 digits addressed from 00H to 0FH
- C7~C0: character code of the CGROM (internal 248 characters) or CGRAM (user-defined 8 characters)
- To specify the character code of the CGROM or CGRAM continuously, only the character code needs to be specified
- The addresses of the DDRAM are automatically incremented by 1.
- The address will be wrapped around to the start address when the DDRAM data write function is successively executed and the DDRAM address is greater than the maximum available address

- Grid positions and set DDRAM addresses

HEX	X3	X2	X1	X0	Grid Position
0	0	0	0	0	G1
1	0	0	0	1	G2
2	0	0	1	0	G3
3	0	0	1	1	G4
4	0	1	0	0	G5
5	0	1	0	1	G6
6	0	1	1	0	G7
7	0	1	1	1	G8
8	1	0	0	0	G9
9	1	0	0	1	G10
A	1	0	1	0	G11
B	1	0	1	1	G12
C	1	1	0	0	G13
D	1	1	0	1	G14
E	1	1	1	0	G15
F	1	1	1	1	G16

Character Generator ROM (CGROM)

- The CGROM for generating character patterns of 5x7 dots from 8-bit character codes generates 248 types of character patterns
- The character codes are shown on the following page
- Character codes 00H to 07H are allocated to the CGRAM



Character Code Table for ROM code 002

Character Code Table for ROM code 003

Character Generator RAM (CGRAM)

The CGRAM stores the pixel information (1=pixel on, 0=pixel off) for the eight user-defined 5x7 characters. Valid CGRAM addresses are 00H to 07H. Character codes 00H~07H are assigned to the user-defined characters.

CGRAM data write command

Byte	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1st	W	0	0	1	*	*	X2	X1	X0
2nd	W	*	C30	C25	C20	C15	C10	C5	C0
3rd	W	*	C31	C26	C21	C16	C11	C6	C1
4th	W	*	C32	C27	C22	C17	C12	C7	C2
5th	W	*	C33	C28	C23	C18	C13	C8	C3
6th	W	*	C34	C29	C24	C19	C14	C9	C4

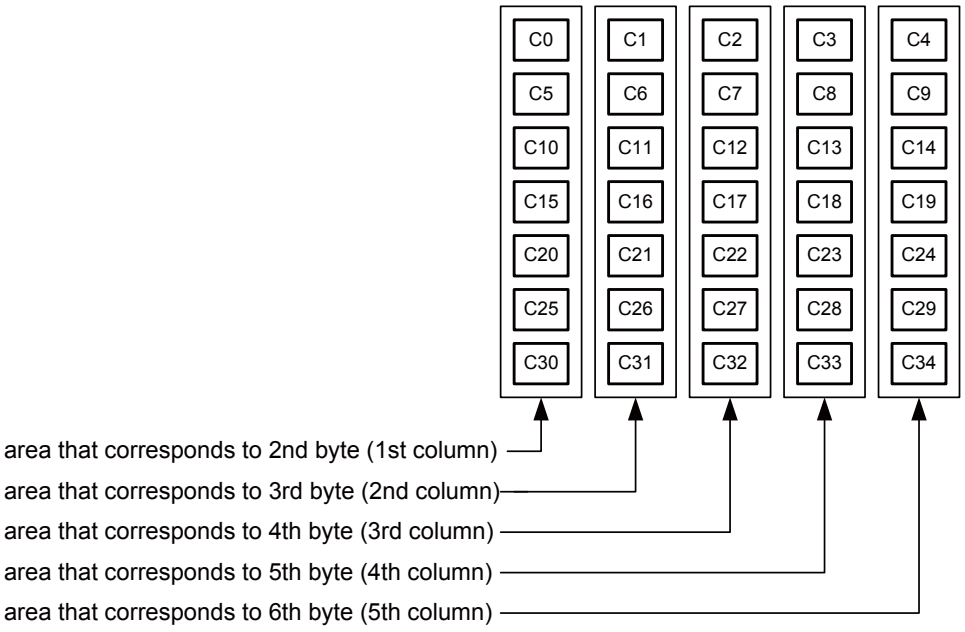
*: Don't care

The CGRAM data write command descriptions are described by the following:

- X2~X0: CGRAM addresses for 8 user-defined characters
- C34~C0: character pattern data, 35-bit outputs per digit. The relationship between the 35-bit character pattern data and the dot positions for each digit is shown in the accompanying diagram
- A character pattern stored in the CGRAM can be displayed and addressed by the character code specified in the DDRAM
- To specify character pattern data continuously, only the character pattern data needs to be specified
- The addresses of the CGRAM are automatically incremented by 1
- The address will be wrapped around to the start address when the CGRAM data write function is successively executed and the CGRAM address is greater than the maximum available address
- CGROM addresses and set CGRAM addresses

HEX	X2	X1	X0	CGRAM	Mapping to CGROM Address
00	0	0	0	RAM00	00000000B
01	0	0	1	RAM01	00000001B
02	0	1	0	RAM02	00000010B
03	0	1	1	RAM03	00000011B
04	1	0	0	RAM04	00000100B
05	1	0	1	RAM05	00000101B
06	1	1	0	RAM06	00000110B
07	1	1	1	RAM07	00000111B

- Relationship between the CGRAM output data and the character dot position



Additional Symbol Display RAM (ADRAM)

The ADRAM stores the additional symbol information (1=symbol on, 0=symbol off) for the 16 digits. For each 5x7 digit there are two symbols displayed together with the character. The positional relationship is shown in the accompanying diagram.

ADRAM Data Write Command

Byte	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1st	W	0	1	0	*	X3	X2	X1	X0
2nd	W	*	*	*	*	*	*	C1	C0
3rd	W	*	*	*	*	*	*	C1	C0
4th	W	*	*	*	*	*	*	C1	C0
:	:	:	:	:	:	:	:	:	:

*: Don't care

The ADRAM data write command descriptions are described by the following:

- X3~X0: ADRAM addresses for 16 digits
- C1~C0: 2 bits Symbol data for each digit
- Symbol data specified by the ADRAM is directly output regardless of the CGRAM data and the CGROM code
- The ADRAM can store 2 types of symbol pattern for each digit
- The ADRAM contents output to the terminal can be used as a cursor for each digit
- The address of the ADRAM is automatically incremented by 1
- The address will be wrapped around to the start address when the ADRAM data write function is successively executed and the ADRAM address is greater than the maximum available address
- Grid positions and ADRAM addresses

HEX	X3	X2	X1	X0	Grid Position
0	0	0	0	0	G1
1	0	0	0	1	G2
2	0	0	1	0	G3
3	0	0	1	1	G4
4	0	1	0	0	G5
5	0	1	0	1	G6
6	0	1	1	0	G7
7	0	1	1	1	G8
8	1	0	0	0	G9
9	1	0	0	1	G10
A	1	0	1	0	G11
B	1	0	1	1	G12
C	1	1	0	0	G13
D	1	1	0	1	G14
E	1	1	1	0	G15
F	1	1	1	1	G16

General Output Port Command

Byte	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1st	W	0	1	1	*	*	*	P2	P1

*: Don't care

The general output port command descriptions are described by the following:

- P2, P1: general output port data
- The general output port supports 2-bit static output operation
- Used to control other I/O devices or control LEDs
- When the general output port data is set to a high level, the related pin will output a VDD voltage level while the related pin will output a GND voltage level when the general output port data is cleared to a low level
- Relationship between the general output port data and the output pin status

P2	P1	Display State of General Output Port	Comment
0	0	Sets P2 to low; Sets P1 to low	—
0	1	Sets P2 to low; Sets P1 to high	—
1	0	Sets P2 to high; Sets P1 to low	—
1	1	Sets P2 to high; Sets P1 to high	Default state when power is applied or when the $\overline{RST}$ input is at a low level.

Display Duty Set Command

Byte	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1st	W	1	0	0	*	*	D2	D1	D0

*: Don't care

The display duty set command descriptions are described by the following:

- D2~D0: Display duty selections
- The display duty adjusts the contrast in 8 stages using 3 selection bits to adjust the pulse width of the segment output.
- The relationship between the setup data and the grid duty is shown in the table.

HEX	D2	D1	D0	Grid Duty	Comment
0	0	0	0	8/16	Default state when power is applied or when $\overline{RST}$ input is at a low level.
1	0	0	1	9/16	—
2	0	1	0	10/16	—
3	0	1	1	11/16	—
4	1	0	0	12/16	—
5	1	0	1	13/16	—
6	1	1	0	14/16	—
7	1	1	1	15/16	—

Number of Digits Set Command

Byte	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1st	W	1	0	1	*	*	K2	K1	K0

*: Don't care

The number of digits set command descriptions is are described by the following:

- K2~K0: number of digit selections
- The number of display digits can be from 9 to 16 digits using the 3 selection bits.
- The relationship between setup data and the displayed grid is shown in the table.

HEX	K2	K1	K0	Number of Digits of Grid	Comment
0	0	0	0	G1 to G16	Default state when power is applied or when the $\overline{RST}$ input is at a low level.
1	0	0	1	G1 to G9	—
2	0	1	0	G1 to G10	—
3	0	1	1	G1 to G11	—
4	1	0	0	G1 to G12	—
5	1	0	1	G1 to G13	—
6	1	1	0	G1 to G14	—
7	1	1	1	G1 to G15	—

All Display Lights On/Off Set Command

Byte	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1st	W	1	1	0	*	D	S	H	L

*: Don't care

The display ON/OFF set command descriptions are described by the following:

- S bit: S="1" is standby mode; S="0" is normal mode
- D bit: D="1" is display ON; D="0" is display OFF
- H bit: set all lights ON
- L bit: set all lights OFF
- When S bit = "1", the internal oscillator stops and all outputs are set to low and the general port is set to high (P2 and P1 are all at high levels)
- When S bit = "1", all registers will keep their original value
- After being woken up, the device will set the S and D bits to "0"
- The "All display lights ON" command is used primarily for display testing
- The "All display lights OFF" command is primarily used for display flashing
- The command bits, including D, H and L bits, cannot control the general output port
- The relationship between the control bits and display state of G1~G16, S1~S35 and AD1~AD2 pins is shown in the table.

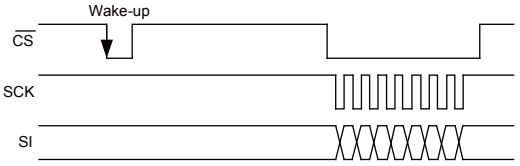
D	S	H	L	Driver Output Status	Comment
1	0	0	0	Normal display	—
1	0	0	1	Sets all segments and Sets all segments and AD to Low. All grids maintain scan General ports active AD to Low	—
1	0	1	*	Sets all segments and AD to High All grids maintain scan General ports active	—
0	0	*	*	Sets all segments and AD to Low Sets all grids to Low General ports active	Display off mode (Default state when power is applied or when the $\overline{RST}$ input is at a low level.)
*	1	*	*	Sets all segments and AD to Low. Sets all grids to Low. Set General ports to high.	Standby mode

*: Don't care

Wake-up Setting

The wake-up behavior is described by the following:

- The device is woken up when a $\overline{CS}$ low pulse is asserted i.e. when a $\overline{CS}$ signal falling edge occurs.
- The D and S control bits described in the preceding section will be set to "0" - display off mode
- The oscillator starts to oscillate after wake-up
- The VFD driver does not display until the host MCU transmits commands to it.



TEST Command

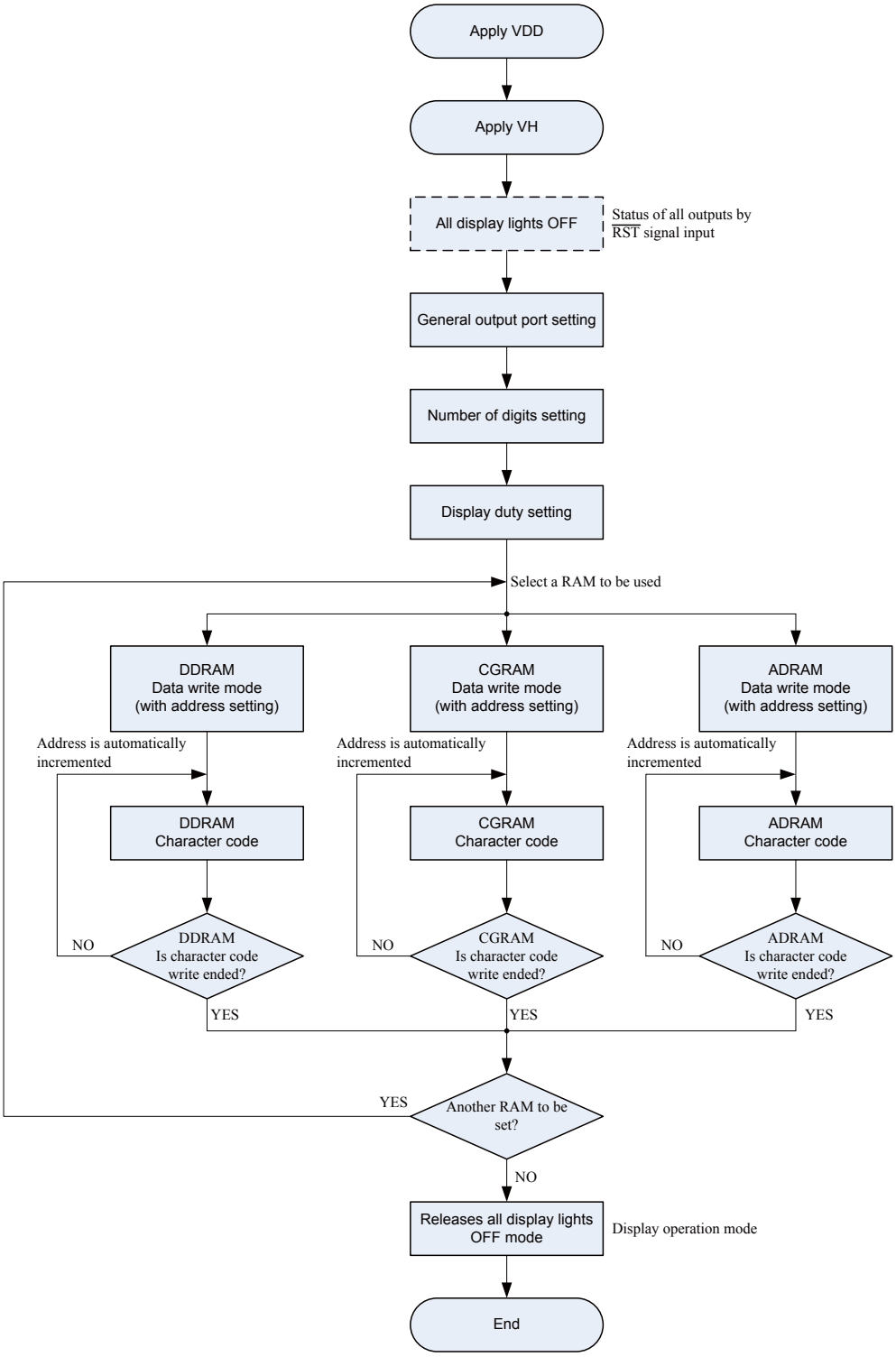
Byte	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1st	W	1	1	1	0	0	0	0	0

The TEST command is described by the following:

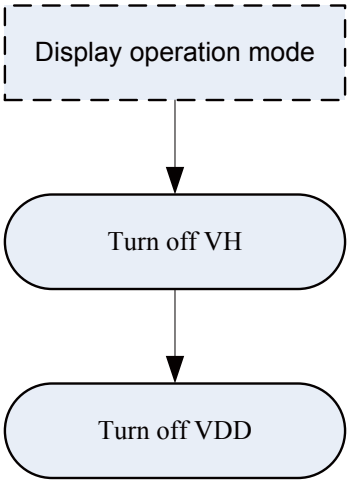
- Only when the TEST pin is high is the TEST command "E0H" is valid
- This command is used by HOLTEK for internal testing.

Setting Flowchart

Power applied included

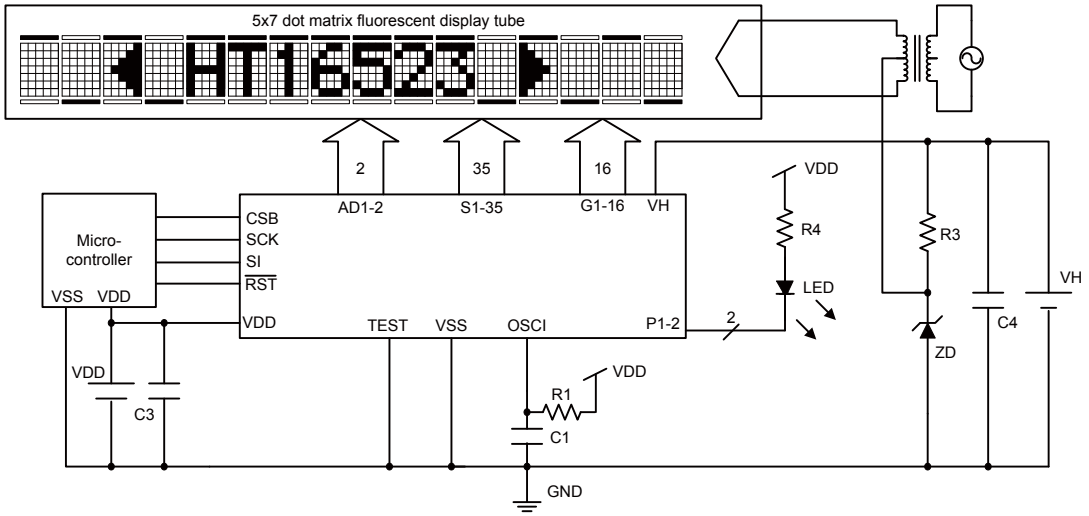


Power-off Flowchart

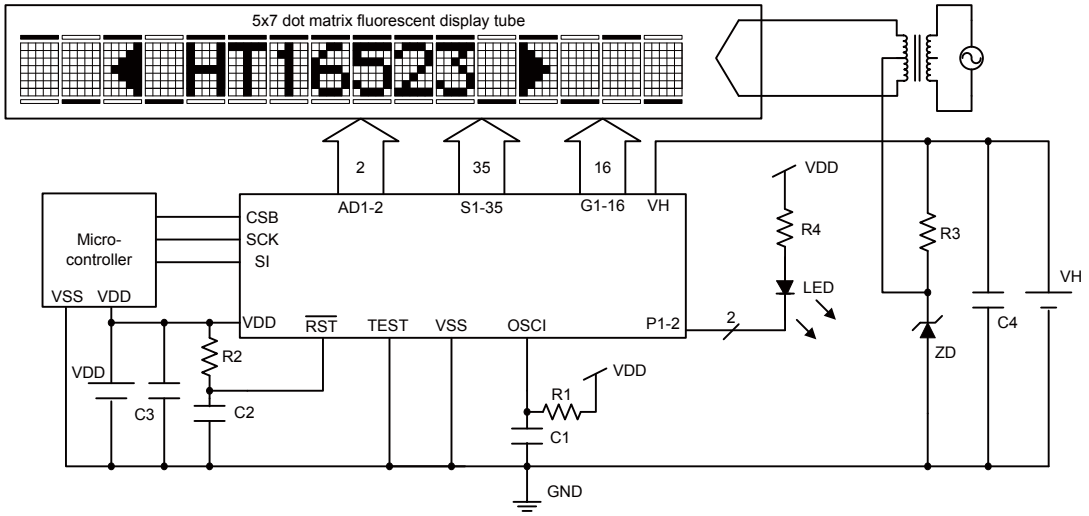


Application Circuit

$\overline{\text{RST}}$ Pin is Connected to a MCU



$\overline{\text{RST}}$ Pin is Connected to External Resistor and Capacitor



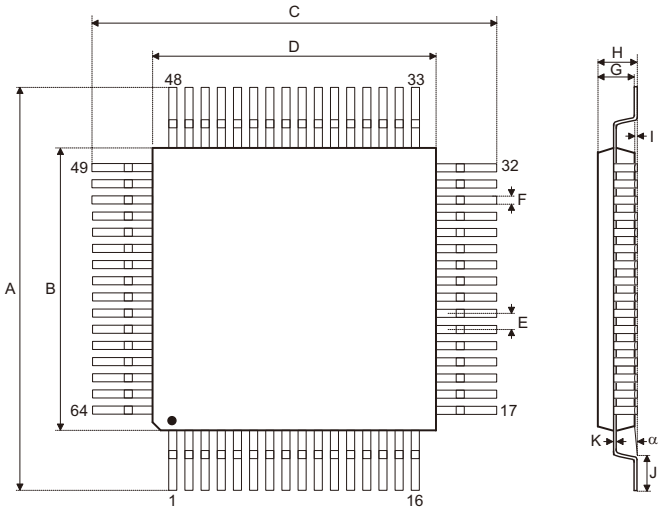
Note: 1. The VDD value depends on the power supply voltage of the microcontroller used. Adjust the values of the components R2, R4, C2, C3 and C4 according to the power supply voltage used.

2. The VH value depends on the fluorescent display tube used. Adjust the values of the components R3 and ZD according to the power supply voltage used.

3. R1=120KΩ, C1=0.1μF.

Package Information

64-pin LQFP (7mm x 7mm) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.350	—	0.358
B	0.272	—	0.280
C	0.350	—	0.358
D	0.272	—	0.280
E	—	0.016	—
F	0.005	—	0.009
G	0.053	—	0.057
H	—	—	0.063
I	0.002	—	0.006
J	0.018	—	0.030
K	0.004	—	0.008
α	0°	—	7°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	8.90	—	9.10
B	6.90	—	7.10
C	8.90	—	9.10
D	6.90	—	7.10
E	—	0.40	—
F	0.13	—	0.23
G	1.35	—	1.45
H	—	—	1.60
I	0.05	—	0.15
J	0.45	—	0.75
K	0.09	—	0.20
α	0°	—	7°

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